High density, high refresh rate LED display module with TLC5958

Design resource: TLC5958 Datasheet and application note

Design features:

- 64 x 64 (R/B/G) LED matrix with 2.5mm high density pixel pitch
- Low Grayscale Enhancement (LGSE™) improve display performance in low grayscale condition
- 1/32 multiplexing ratio result in only 8pcs TLC5958 needed
- Cost effective compare with traditional 16-CH driver solution. 48-CH TLC5958 simplify PCB layout, only 4-layer PCB needed
- 3.5kHz high refresh rate with max 33MHz GCLK input
- ~14bit grayscale with max 33MHz GCLK input
- Better EMI performance due to internal GCLK double edge function, which allows lower board level GCLK frequency
- TLC5958 built-in SRAM allows lower SCLK frequency(6MHz in case 4pcs 5958 cascading)
- 512 step adjustment for each color to get best white balance by software
- Pre-charge FET make sure Ghost free display
- High system reliability (LED open detection, thermal shutdown)
- Low system power consumption (Power save mode, low knee voltage)
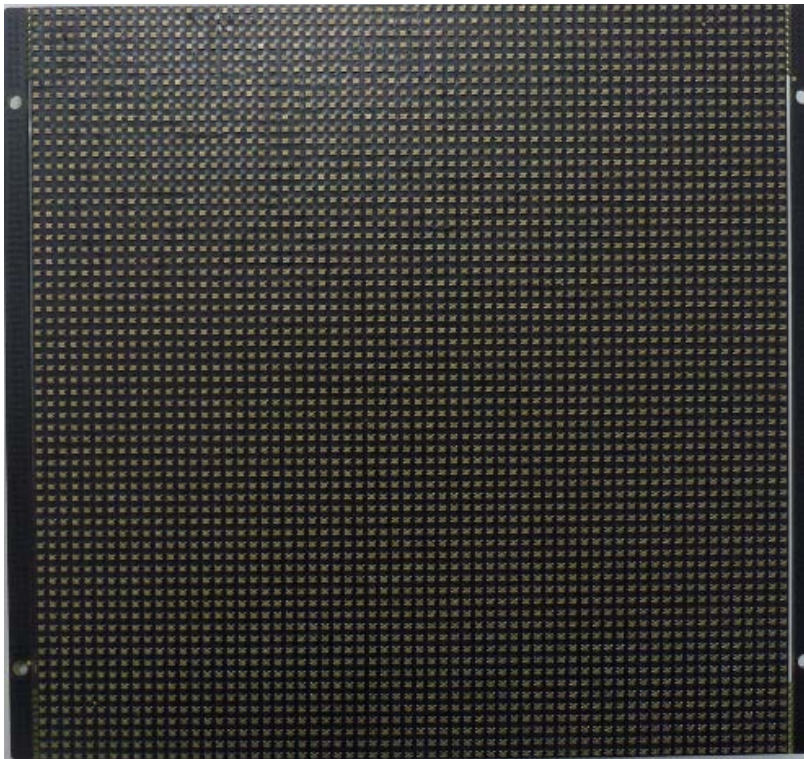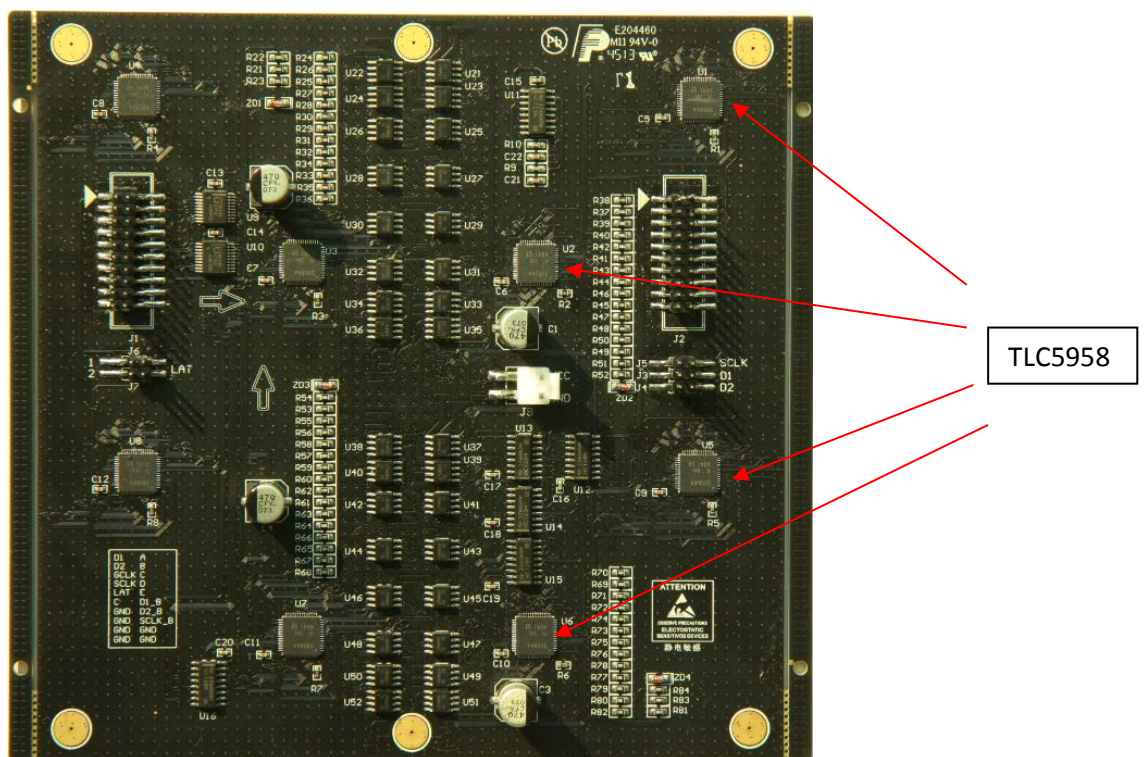- Support multiple modules cascading

Fig1. Top view of LED module

TLC5958

Fig2. Bottom view of LED module

System description

This LED module is 64 x 64 pixel size high density LED display module, pixel pitch is 2.5mm. TI's new generation 48 channel LED driver TLC5958 is used to drive this LED matrix. TLC5958 has 48kbit SRAM embedded, can support maximum 1/32 multiplexing ratio. With this high multiplexing ratio, only 8pcs TLC5958 is needed in this module. Compare with traditional 16 channel LED drivers, only 1/3 quantity of drivers are used. TLC5958 pin-out is optimized for easy PCB layout, thus only 4-layer PCB is used, comparing the traditional 6-layer PCB. All of these reduced the PCB manufacture and assemble cost significantly.

This module support maximum 33MHz Grayscale clock (GCLK) input, result about 3.5kHz visual refresh rate even with this 1/32 high multiplexing ratio. With the intelligent GCLK double edge function of TLC5958, the board level GCLK input frequency can be halved to 16.5MHz while maintain the high refresh rate un-changed, thus the total EMI performance is improved. Furthermore, with the embedded SRAM of TLC5958, the GS data input clock (SCLK) frequency can be greatly decreased. E.g, consider 4pcs TLC5958 cascaded, 60Hz frame rate, then SCLK can be as low as 6MHz. This also improve the board level EMI performance.

For this high density, high multiplexing LED panel, the serious parasitic capacitance of LEDs will cause some visual effect, especially in low grayscale condition, such as 1st line dark issue, red color issue. TLC5958 has proprietary Low Grayscale Enhancement (LGSE^{TM}) function, can improve the display performance at low grayscale condition significantly.

TLC5958 have 512 steps adjustment (CC) for each color group, which is fine enough to get best white balance by software program conveniently. Besides, 8 steps global brightness control (BC) function is also implemented. Users can change the brightness of whole panel easily.

Pre-charge FET built in TLC5958 make sure Ghost free display

To make a high reliability system, some protection function is included. Such as, LED open detection, Iref resistor short protection, thermal shutdown protection, etc.

To minimize the total system power consumption, TLC5958 is designed with low knee-voltage feature, typical 0.32V at 10mA output condition. This means that lower supply voltage for LED anode can be used. Furthermore, power save mode is built in TLC5958. If all '0' GS data input for one 5958, this chip will enter power save mode, the current consumption will reduced to ~ 1/25 of normal condition.

By using TLC5958, the high uniformity of the sink current among different channel and different chips are achieved. For small pixel-pitch LED display panel, LED current is usually small. The requirement of the current mismatch between channel-to-channel, device-to-device need be more tight (less than 3%), otherwise visual brightness difference may be observed. This module guarantee +/-3% C-C mismatch and +/-2% D-D mismatch, thus to make sure the uniformity of brightness among all chips.

Below is the system specification summary.

Item	Specification	Note
Module size	64 x 64 pixel	
Pixel pitch	2.5mm	
Multiplexing ratio	1/32	
Visual refresh rate	3.57kHz	33MHz GCLK, 1uS dead time
Grayscale	~14bit	33MHz GCLK, 1uS dead time, 60Hz frame rate
Data port number	2	
Cascading number per data port	4pcs	
Max input GCLK	33MHz	
Max input SCLK	25MHz	
Input voltage	5V	
Suggested R/G/B LED current	10mA/5mA/4mA	Estimated brightness is 1300cd/m^2
Input current at full brightness	2.6A	R/G/B current is 10/5/4mA
Current mismatch(Channel-to-channel in each TLC5958)	< +/-3%	
Current mismatch (Device-to-device)	< +/-2%	
LED open detection	Yes	
Iref resistor short protection	Yes	
Thermal shutdown	170C typical	

User guide to this module

Module architecture

Below picture illustrates the architecture of this module:
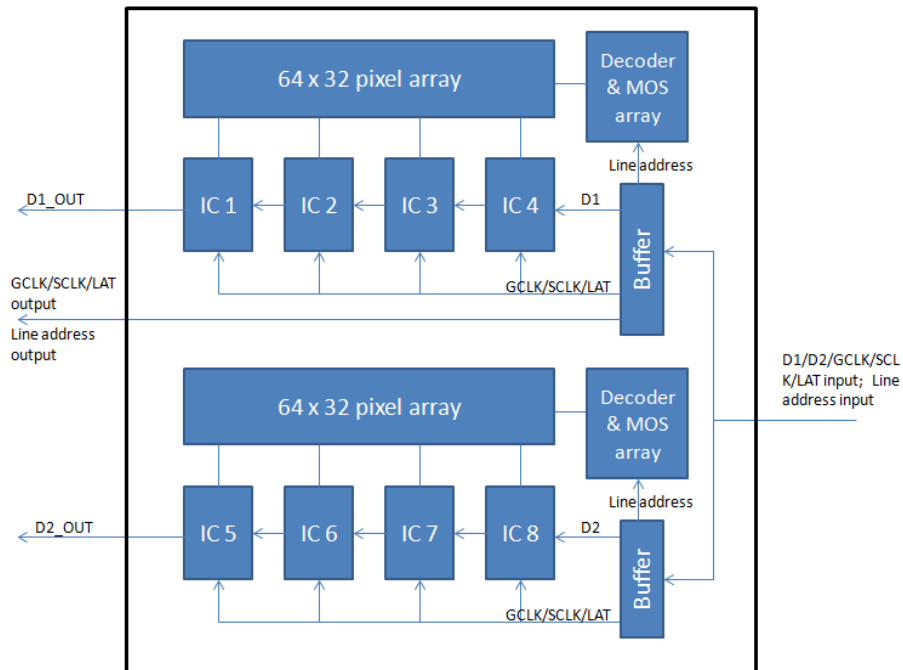
The whole module is divided into two parts, each include 64x32 pixel size, driven by 4pcs TLC5958 in series. Each 4pcs TLC5958 group have one GS data input port.

74HC245 is used as buffer for all the input signal.

TI CD74HC138 is used as decoder for line address input. The output of 74HC138 will turn on one proper line MOSFET to provide supply voltage to one line of LEDs at one moment.

Harvatek's full color common anode LED is used to build up this matrix. The 1mm square size make it a good choice for fine pitch LED display application.

Build larger size panel by cascading modules

This module can be cascaded easily to build up larger size LED display panel. Below picture shows example of 128 x 128 pixel size panel:
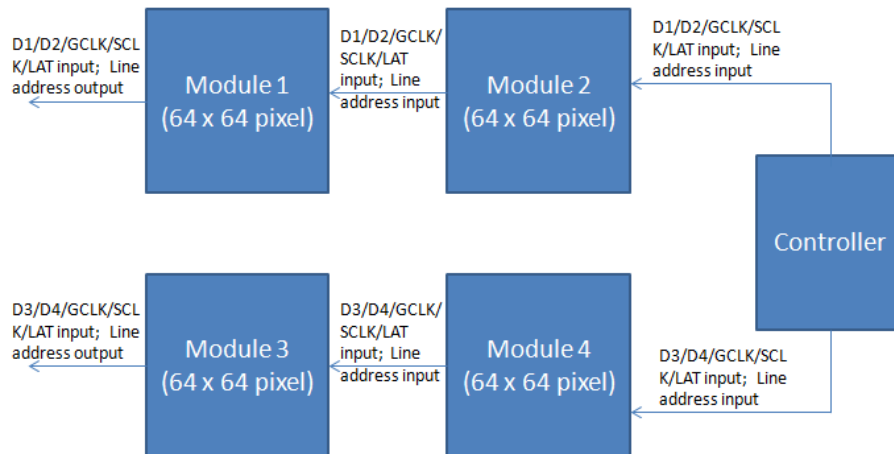
Module 1 and 2 are cascaded, use two GS data input ports D1 and D2. Same case for module 3 and 4. Because the total GS data transferred during one frame period is doubled, the minimum SCLK frequency should also be doubled.
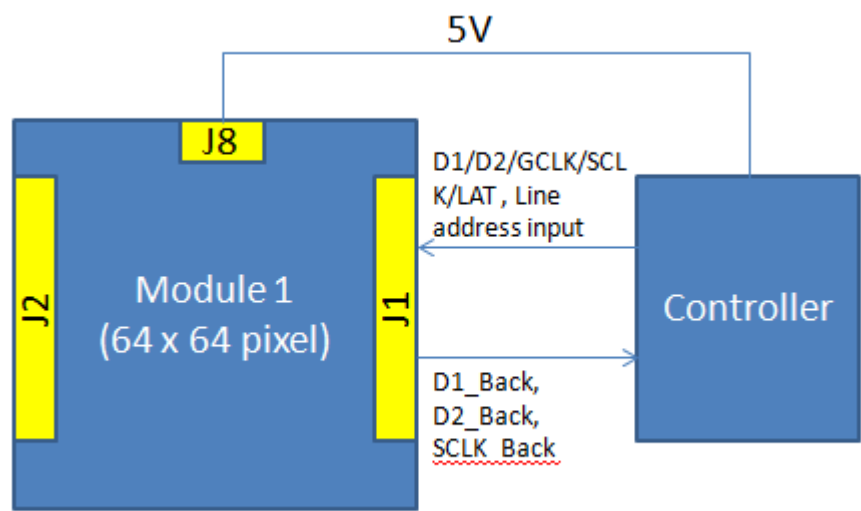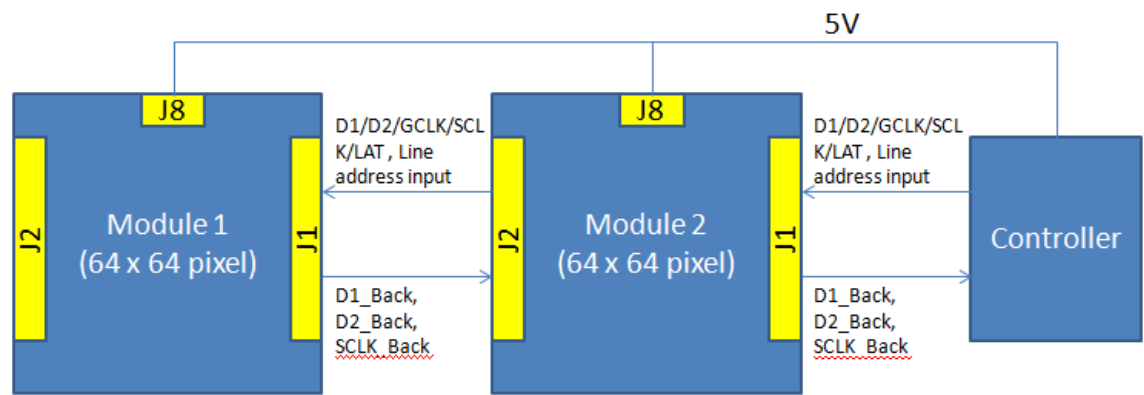
How to use this module?

Condition1: No module cascading, no LOD readback
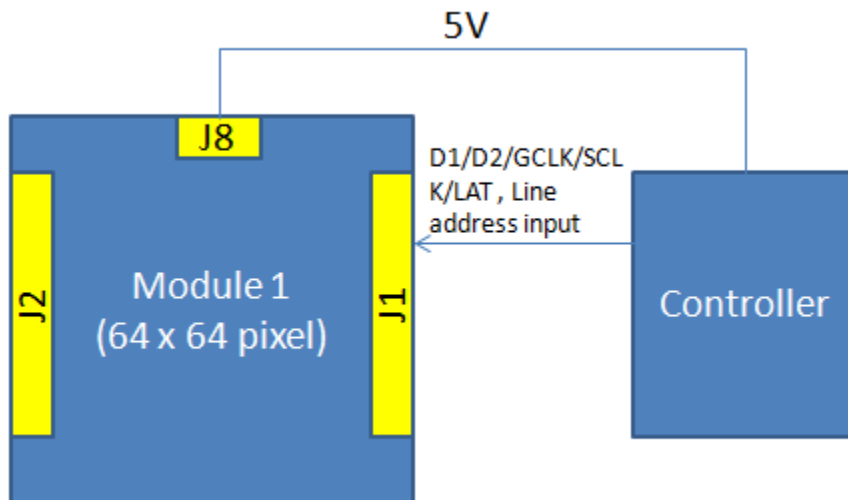
Jumper	Setting
J6, J7	Short
J3, J4, J5	Open

Condition2: No module cascading, need LOD readback

Jumper	Setting
J6, J7	Short
J3, J4, J5	Short

Condition3: two modules cascaded, need LOD readback

Module 1 jumper setting as below:

| Jumper	Setting
J6, J7	Short
J3, J4, J5	Short

Module 2 jumper setting as below:

Jumper	Setting
J6, J7	Short
J3, J4, J5	Open

Test result

1. Low grayscale performance comparison (1st line issue and red color issue)

Below picture: GCLK=20.8MHz, LGSE function turn off.

Whole panel appears a little red at low grayscale condition

1st line dark issue

Below picture: GCLK=20.8MHz, LGSE function turn on to compensate blue/green LED.

Good white balance at low grayscale condition. Also no 1st line dark issue anymore

Test result

1. Low grayscale performance comparison (1st line issue and red color issue)

Below picture: GCLK=20.8MHz, LGSE function turn off.
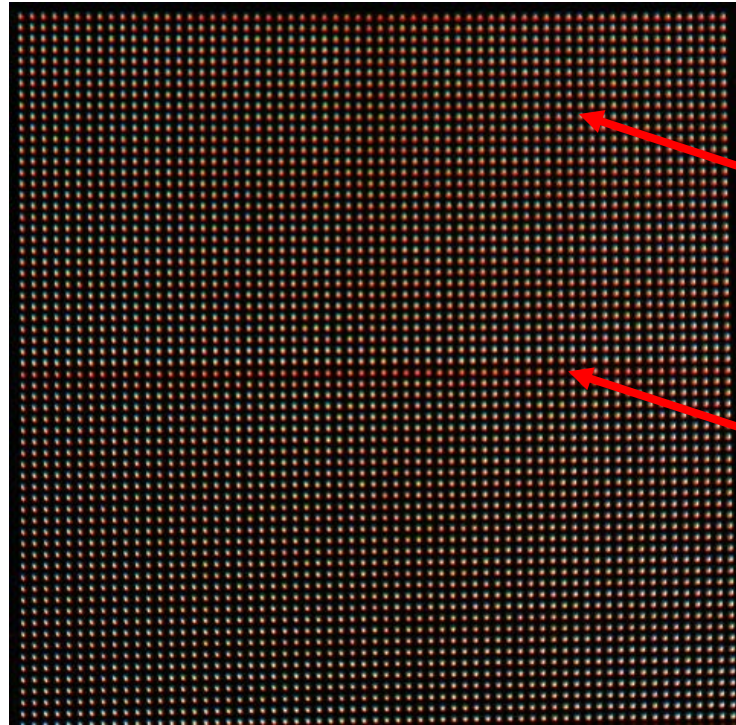
Whole panel appears a little red at low grayscale condition

1st line dark issue

Below picture: GCLK=20.8MHz, LGSE function turn on to compensate blue/green LED.
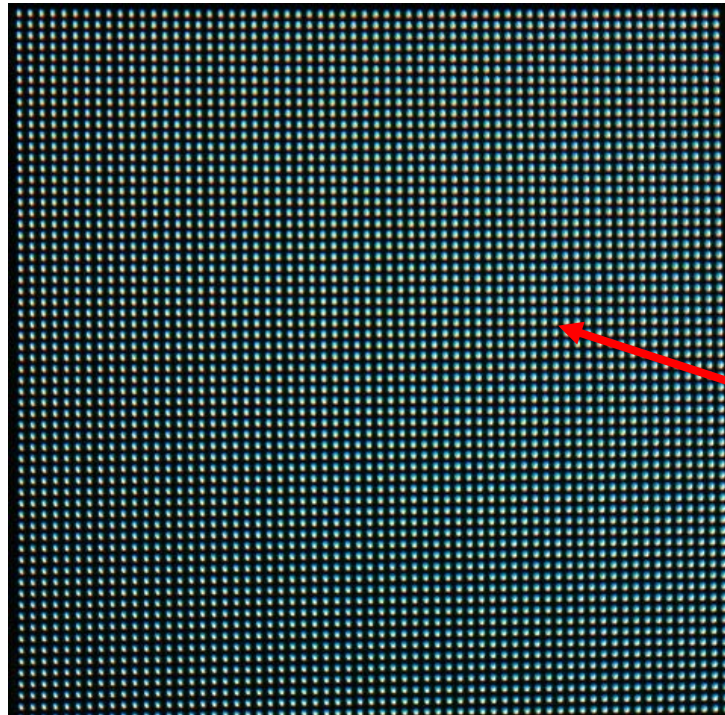
Good white balance at low grayscale condition. Also no 1st line dark issue anymore

2. Low grayscale performance comparison (uniformity issue)
   Below picture: GCLK=20.8MHz, LGSE function turn off.
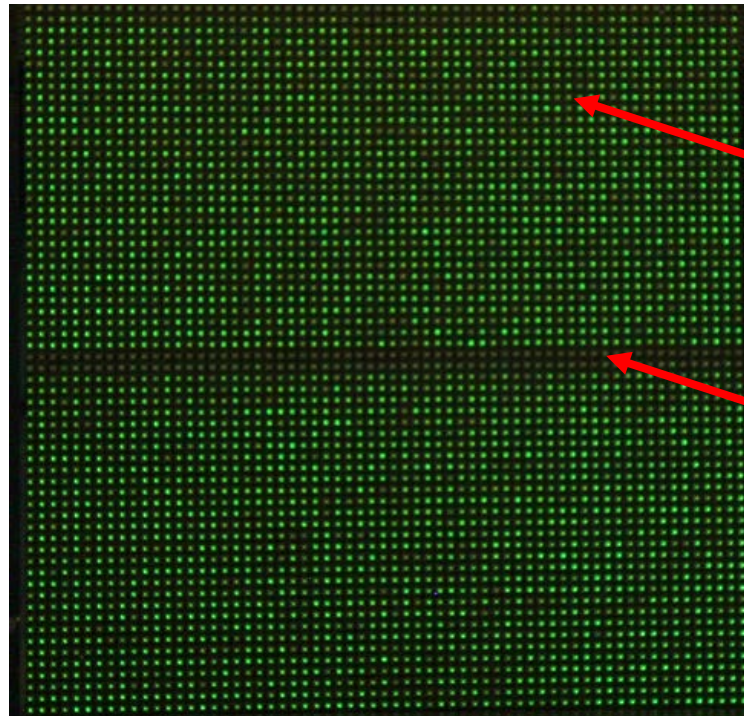
Bad uniformity at low grayscale condition
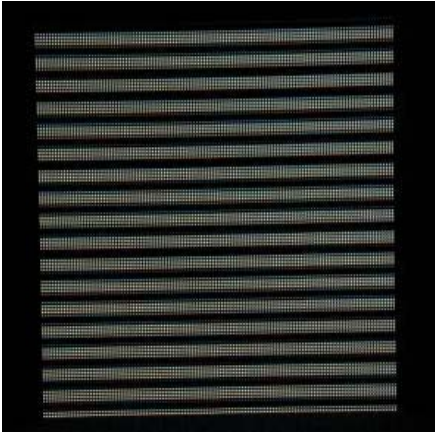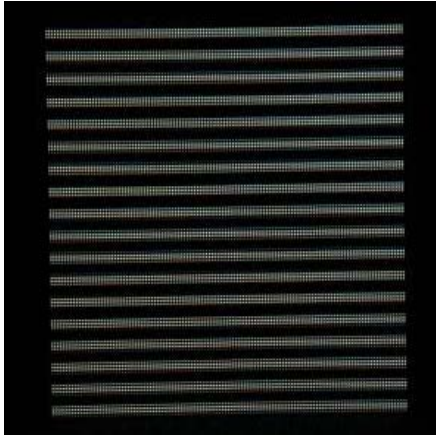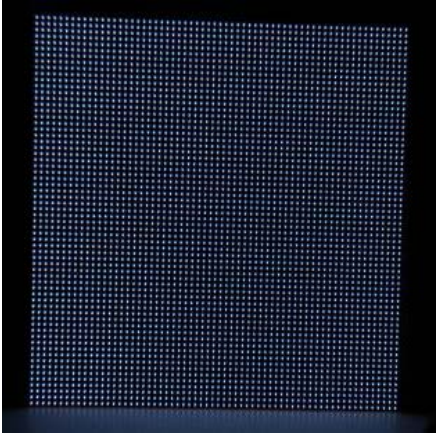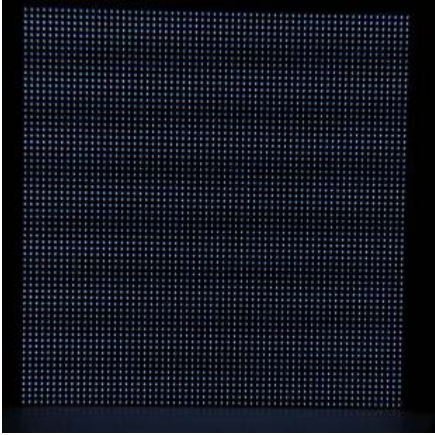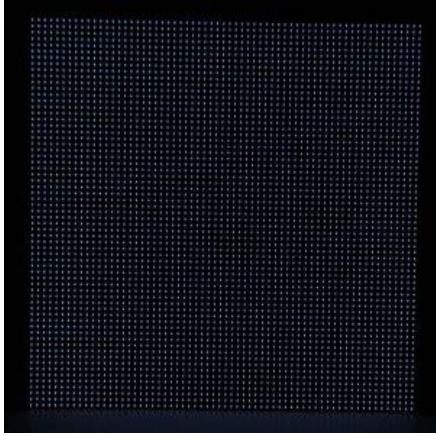
1st line dark issue

Below picture: GCLK=20.8MHz, LGSE function turn on to compensate blue/green LED.
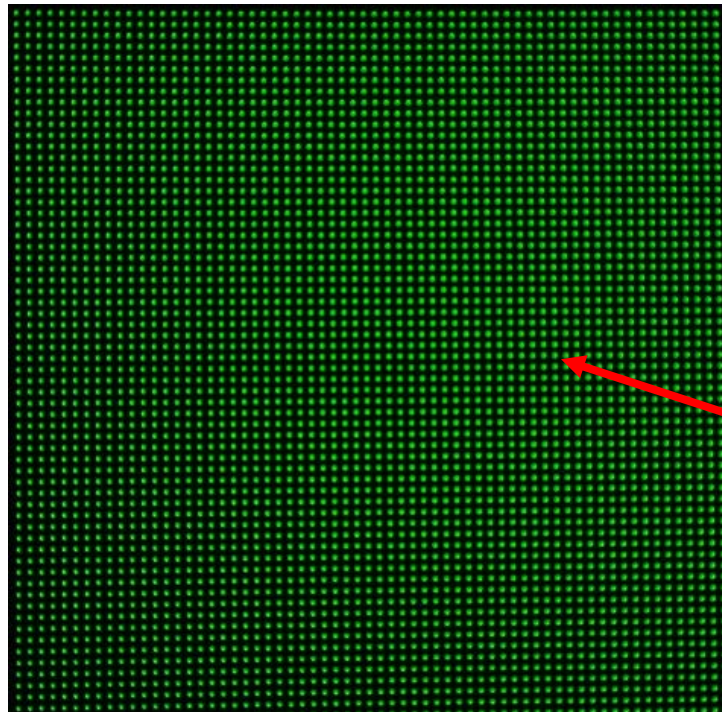
Good uniformity at low grayscale condition. Also no 1st line dark issue anymore

3. Refresh rate comparison

Below comparison, a traditional PWM IC start showing black bands because of slow refresh rate captured by high speed camera shutter.
On the other hand, TLC5958 LED module, with GCLK=25MHz. we see no black bands thanks to its fast refresh rate.

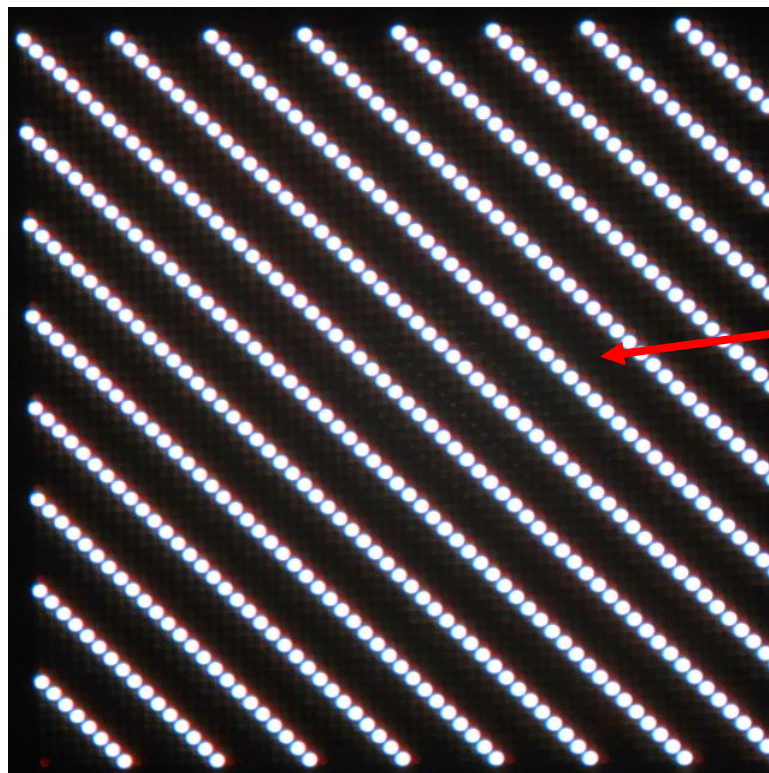|	Shutter Speed		
	1000	**2000**	**3200**
Traditional LED Drivers			
TLC5958			

4. Ghost phenomena comparison

Below picture: traditional PWM IC w/o pre-charge FET, 1/8 multiplexing ratio.
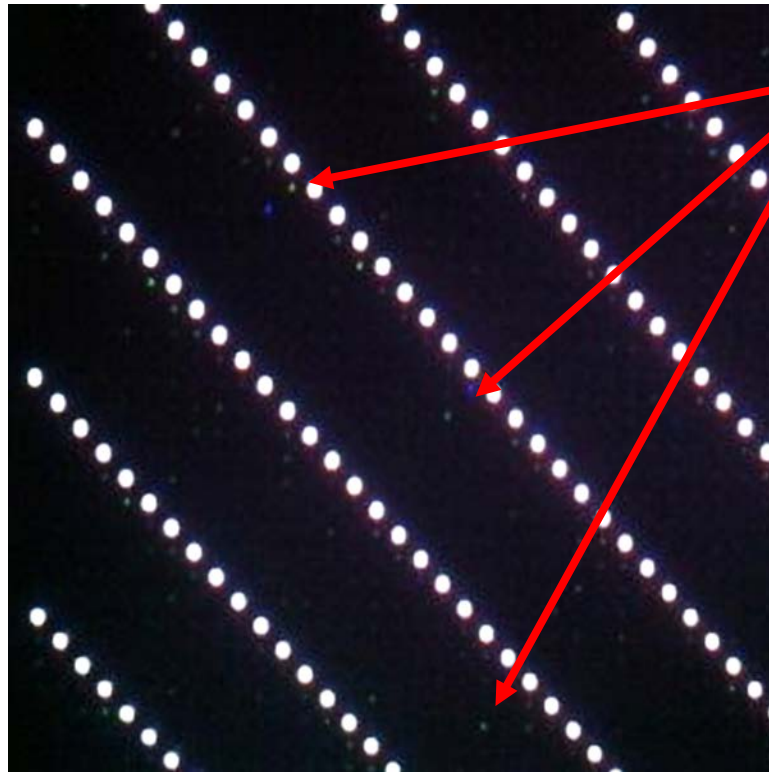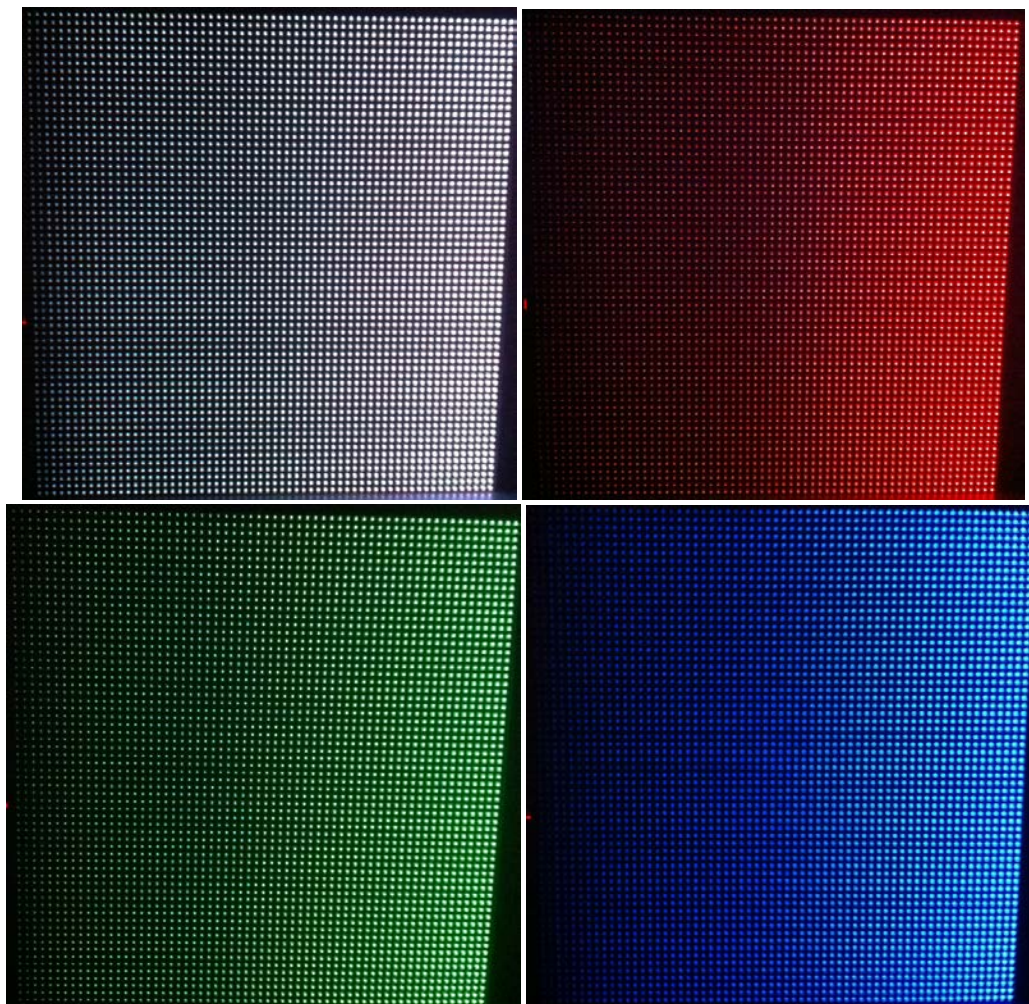

No pre-charge FET. Ghost observed.

Below picture: TLC5958 LED module with pre-charge FET, 1/32 multiplexing ratio
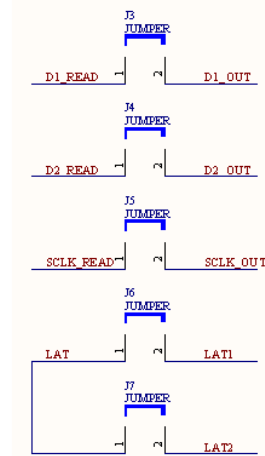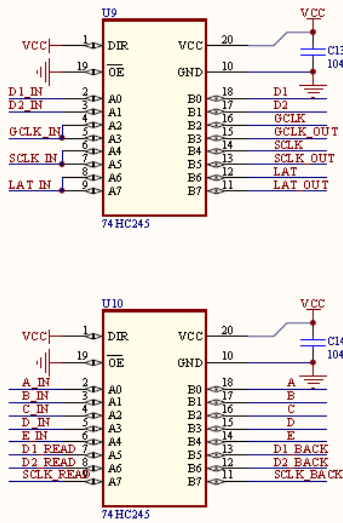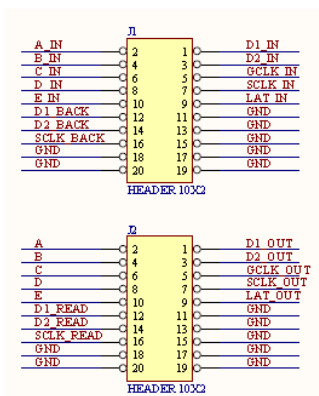

TLC5958 have pre-charge FET inside. No ghost phenomena observed.

5. Some picture of 256 step grayscale changing pattern. Tested with 20.8MHz GCLK, LGSE function turn on.
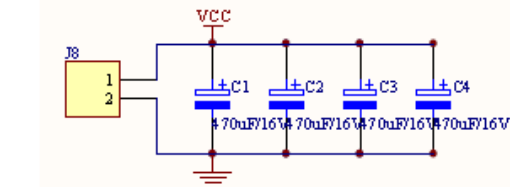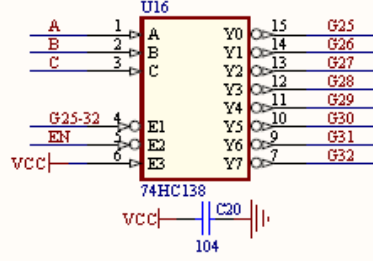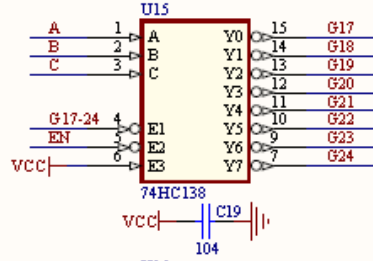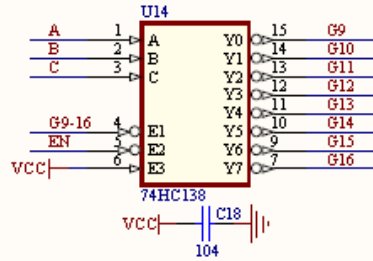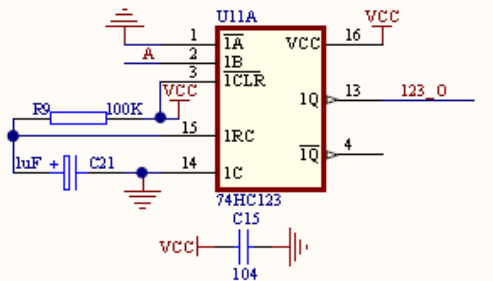
Schematic of this module

Input/output connector and buffer:

Line address decoder and protection circuit:
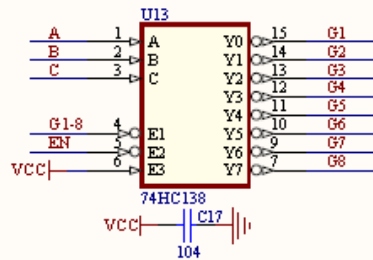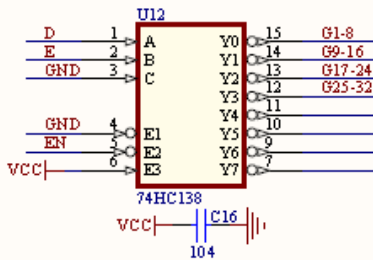
TLC5958 driver (4pcs shown)
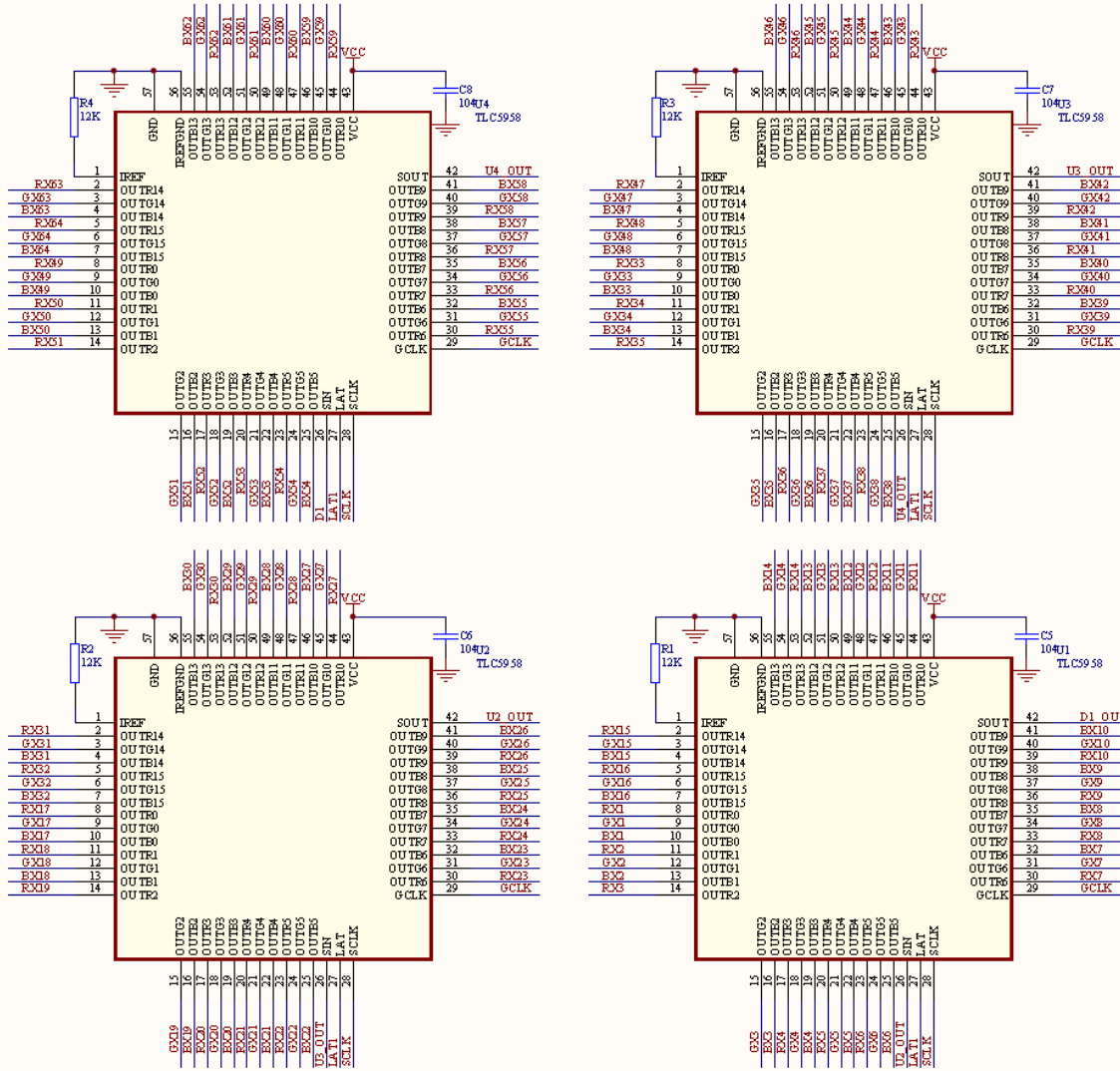
Line MOSFET circuit (partial):

LED matrix (partial)

LED 1
LED 1.Sch

RX[64..1]
GX[64..1]
BX[64..1]
L[16..1]

RX[64..1]
GX[64..1]
BX[64..1]
L[16..1]

LED 2
LED 2.Sch

RX[64..1]
GX[64..1]
BX[64..1]
L[32..17]

RX[64..1]
GX[64..1]
BX[64..1]
L[32..17]

LED 3
LED 3.Sch

RX[128..65]
GX[128..65]
BX[128..65]
L[48..33]

RX[128..65]
GX[128..65]
BX[128..65]
L[48..33]

LED 4
LED 4.Sch

RX[128..65]
GX[128..65]
BX[128..65]
L[64..49]

RX[128..65]
GX[128..65]
BX[128..65]
L[64..49]

L1

D1 D2 D3 D4 D5 D6 D7 D8 D9
R G B

RX1 GX1 BX1
RX2 GX2 BX2
RX3 GX3 BX3
RX4 GX4 BX4
RX5 GX5 BX5
RX6 GX6 BX6
RX7 GX7 BX7
RX8 GX8 BX8
RX9 GX9 BX9

L2

D65 D66 D67 D68 D69 D70 D71 D72 D73
R G B

RX1 GX1 BX1
RX2 GX2 BX2
RX3 GX3 BX3
RX4 GX4 BX4
RX5 GX5 BX5
RX6 GX6 BX6
RX7 GX7 BX7
RX8 GX8 BX8
RX9 GX9 BX9

PCB layout

Top layer

Mid-layer1

Mid-layer2

Bottom layer

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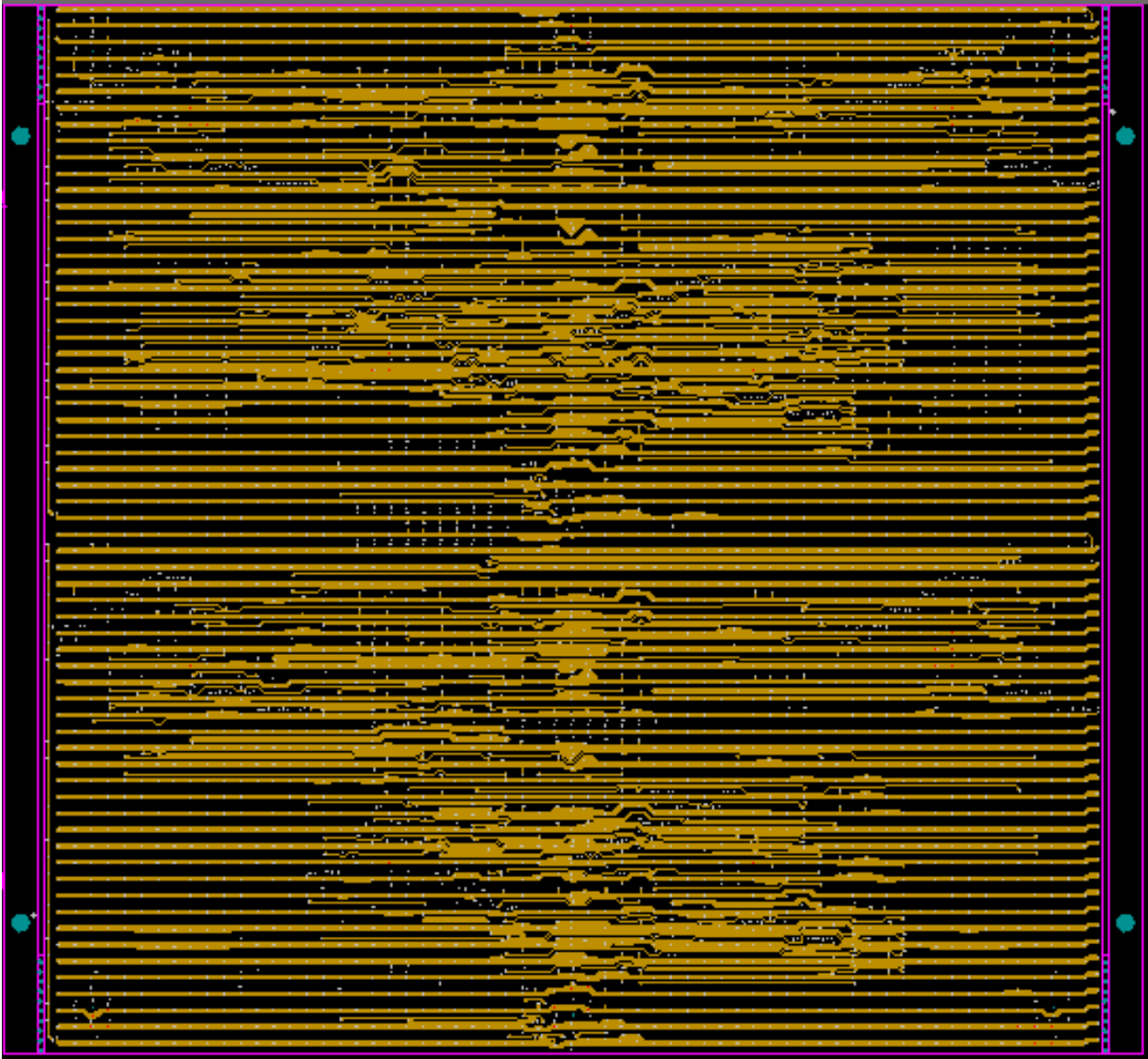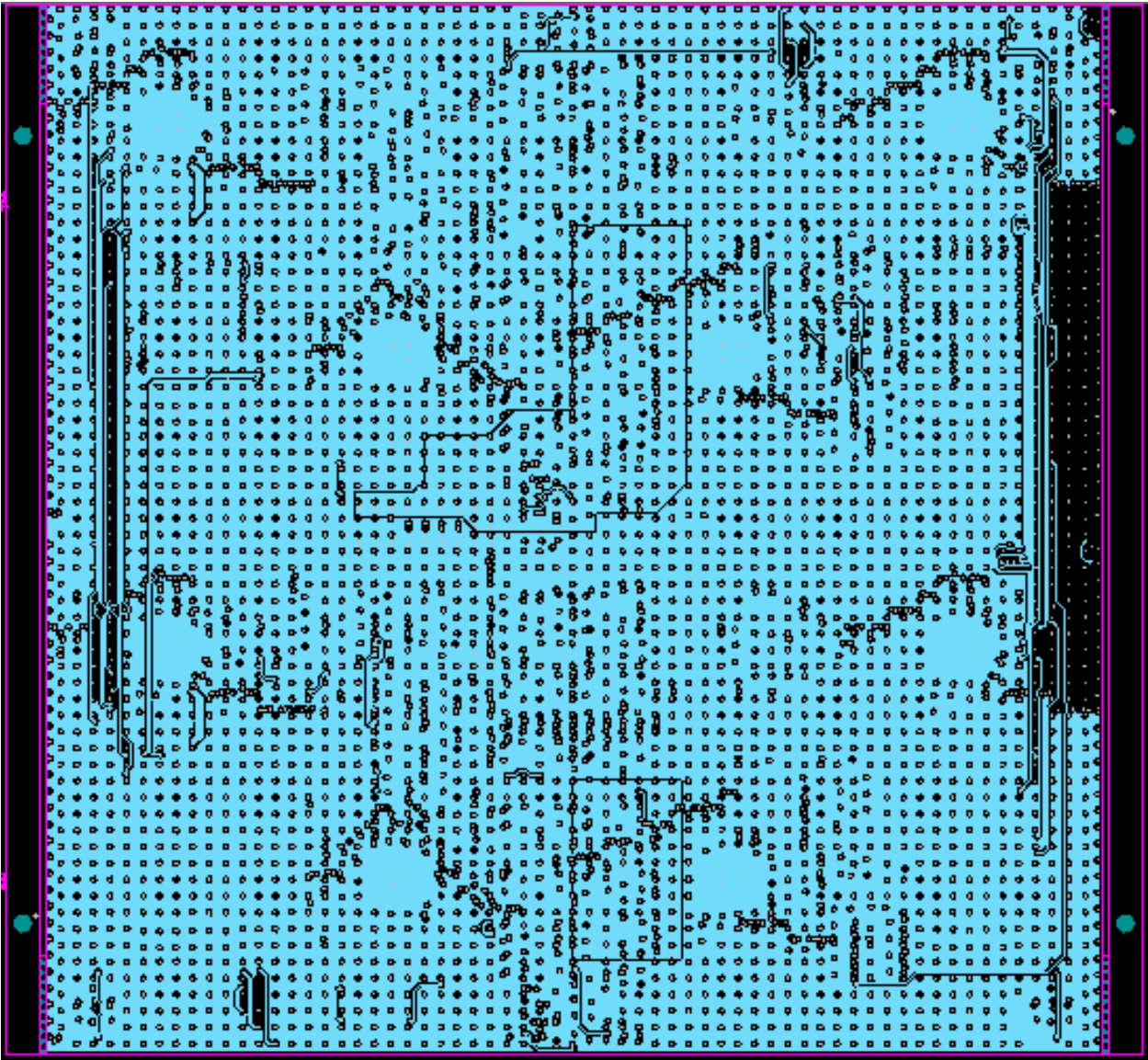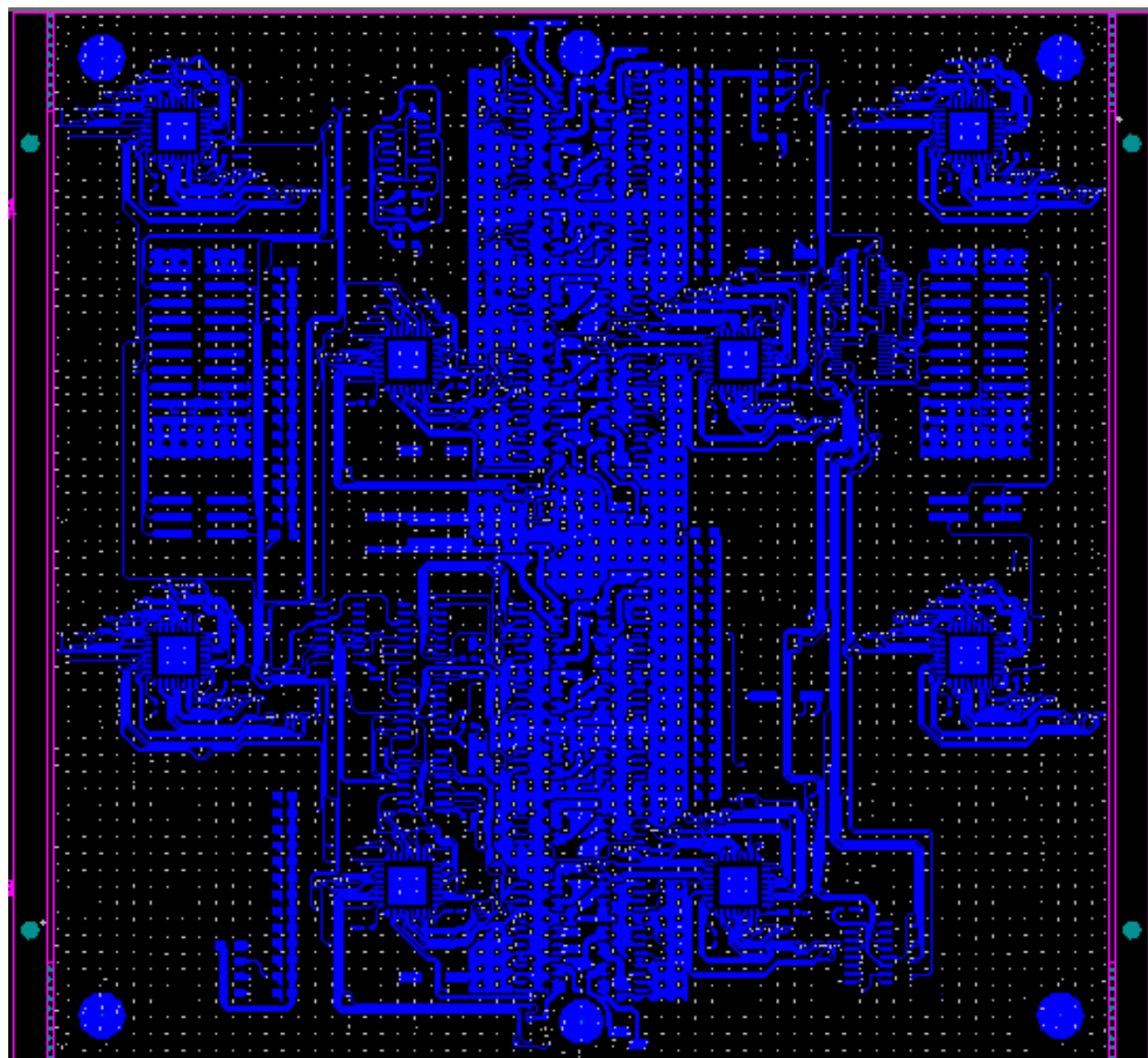
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